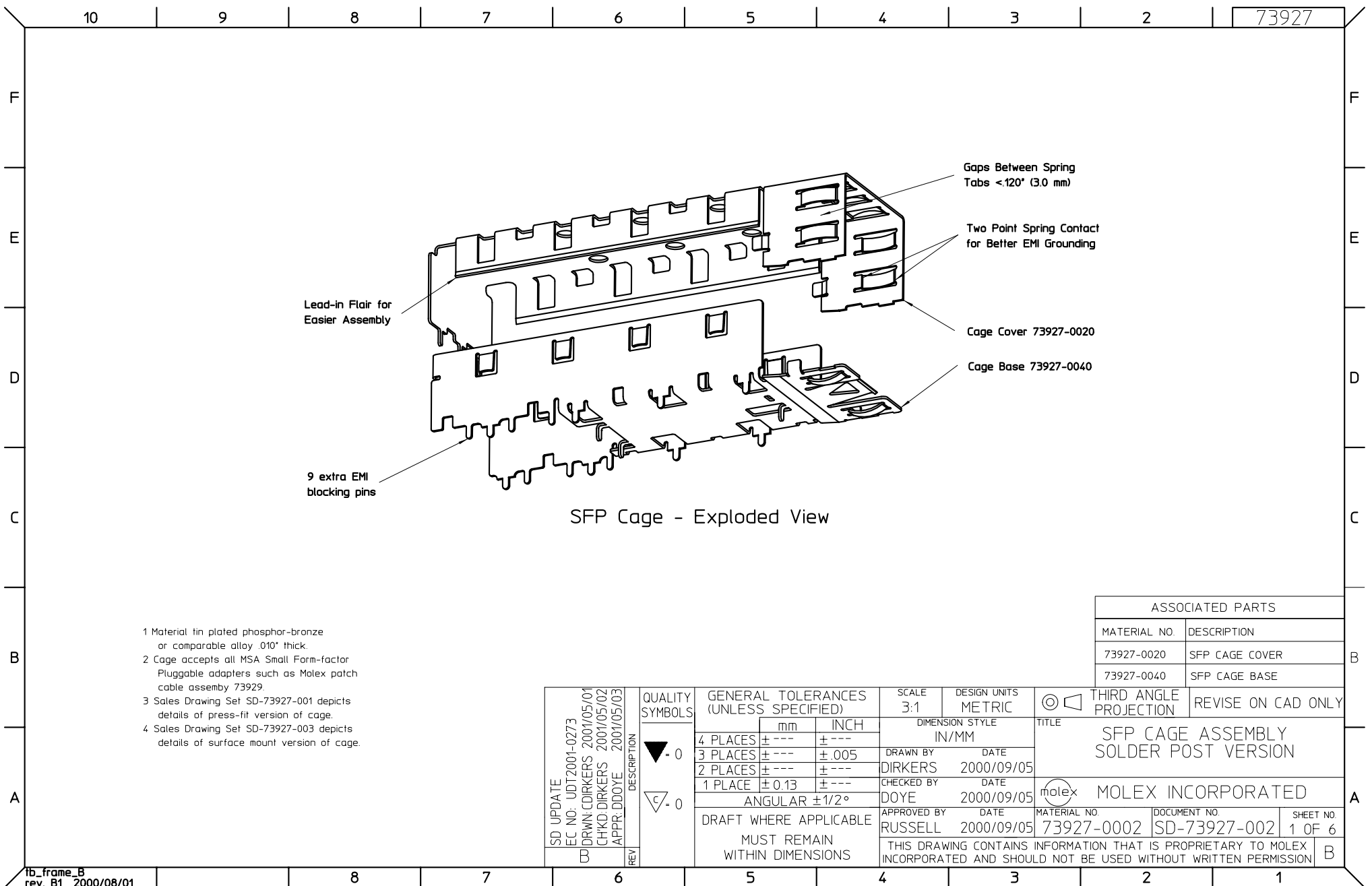
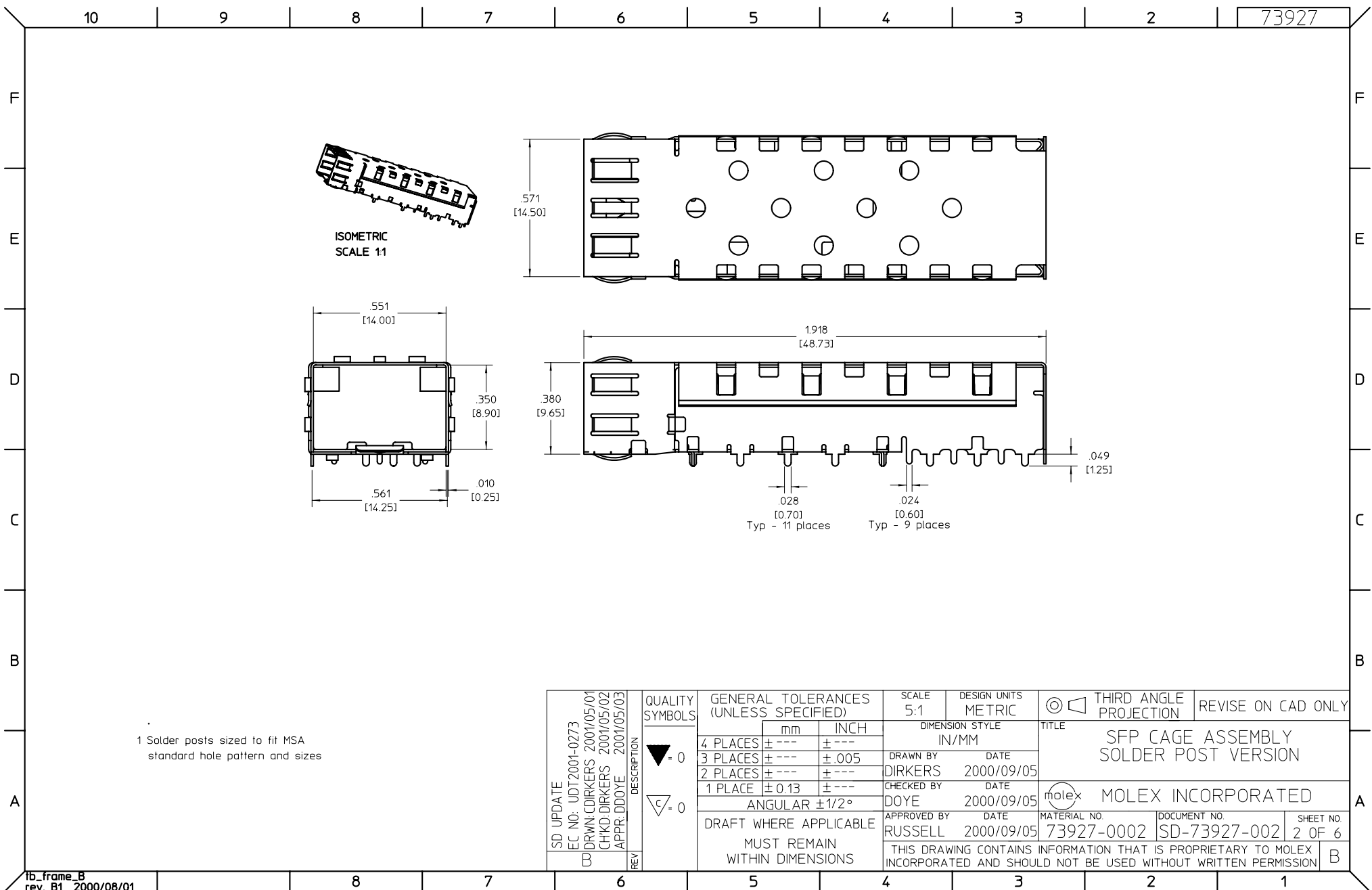
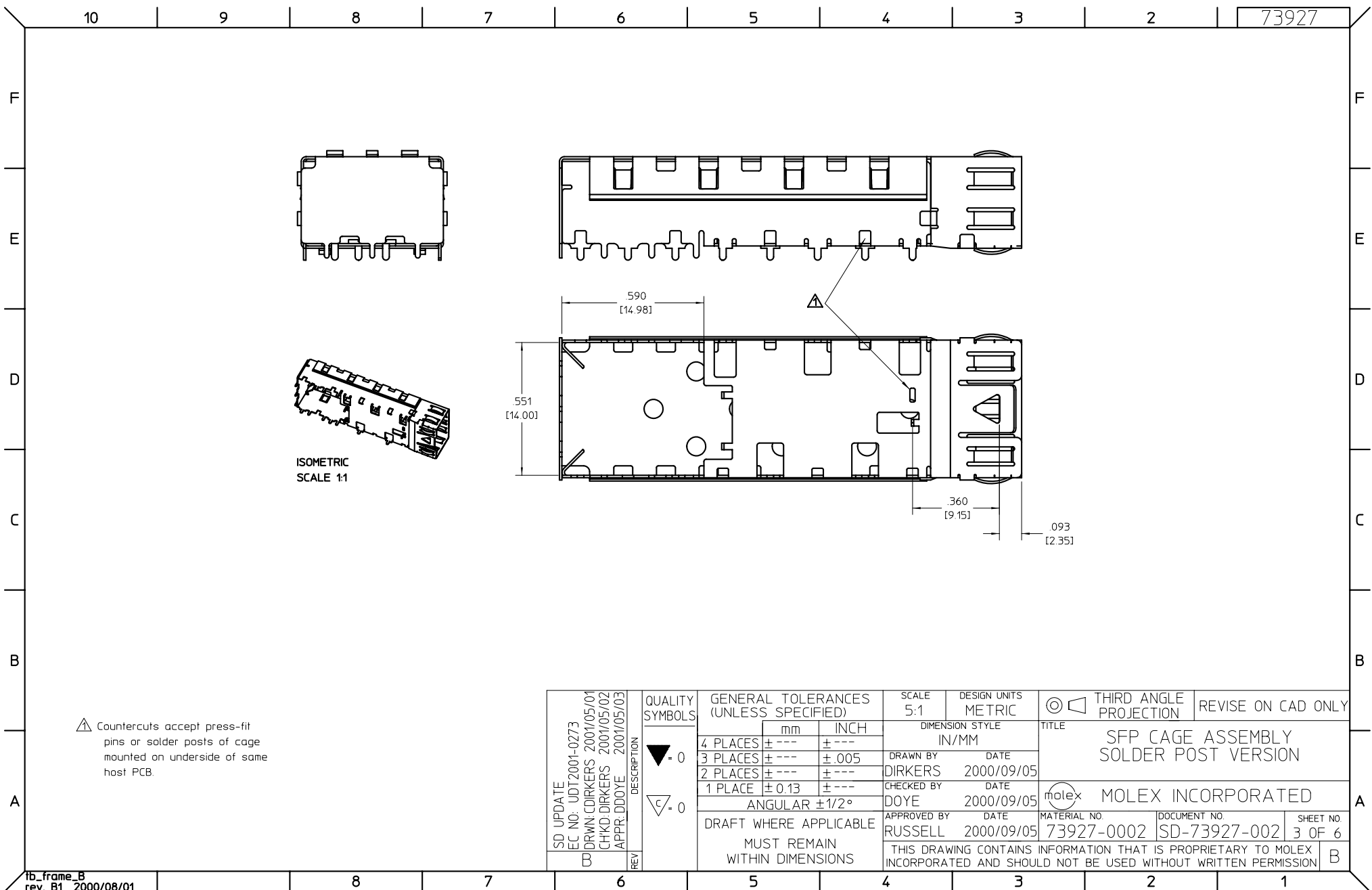






1 Solder posts sized to fit MSA
standard hole pattern and sizes

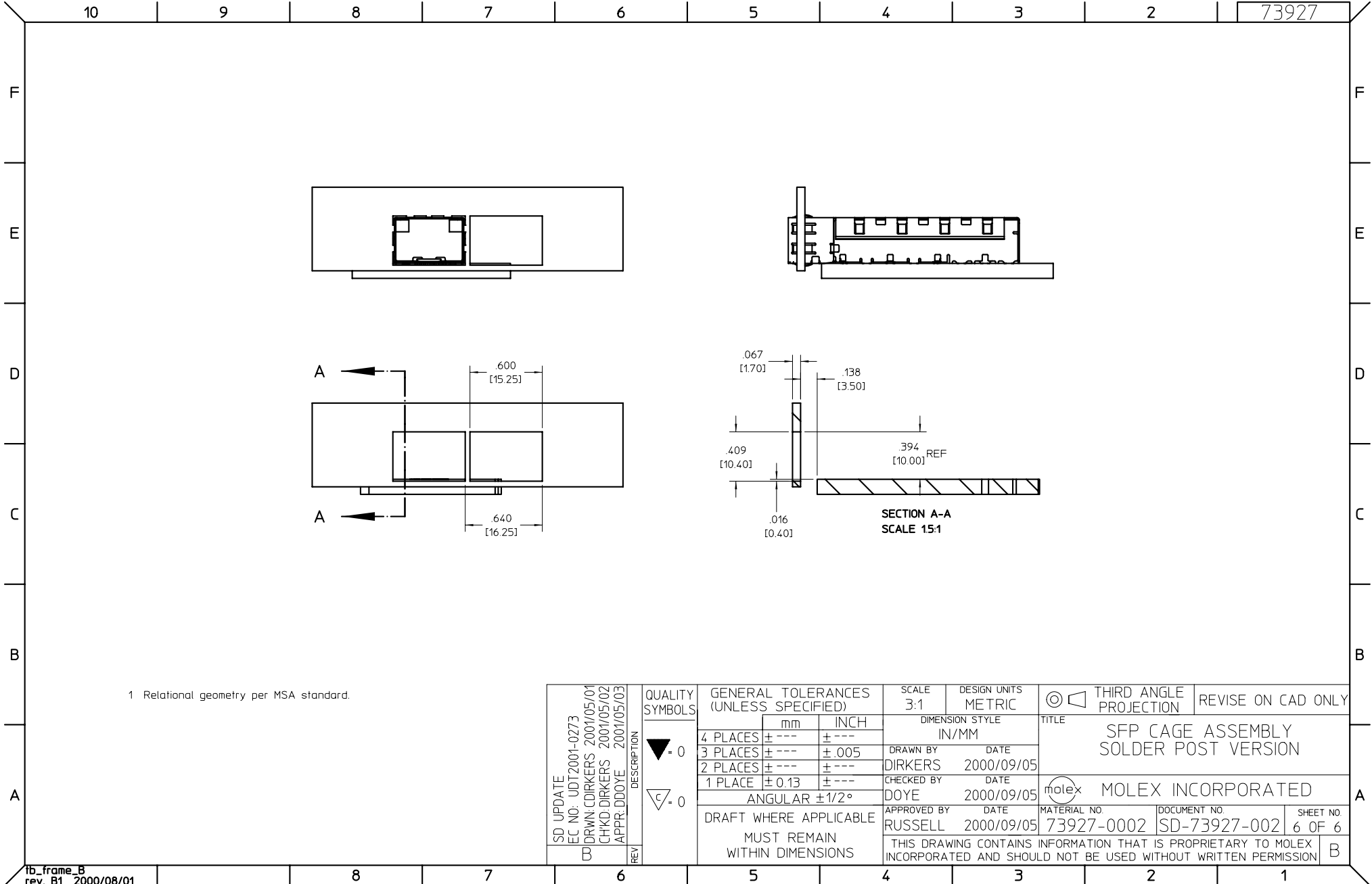
SD UPDATE EC NO: UDT2001-0273 DRWN: DIRKERS 2001/05/01 CHKD: DIRKERS 2001/05/02 APPR: DOOYE 2001/05/03	REV	DESCRIPTION	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		REVISE ON CAD ONLY			
						DIMENSION STYLE IN/MM		TITLE SFP CAGE ASSEMBLY SOLDER POST VERSION					
						DRAWN BY DIRKERS						DATE 2000/09/05	
						CHECKED BY DOYE						DATE 2000/09/05	
						APPROVED BY RUSSELL		DATE 2000/09/05		MATERIAL NO 73927-0002		DOCUMENT NO SD-73927-002	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								B	





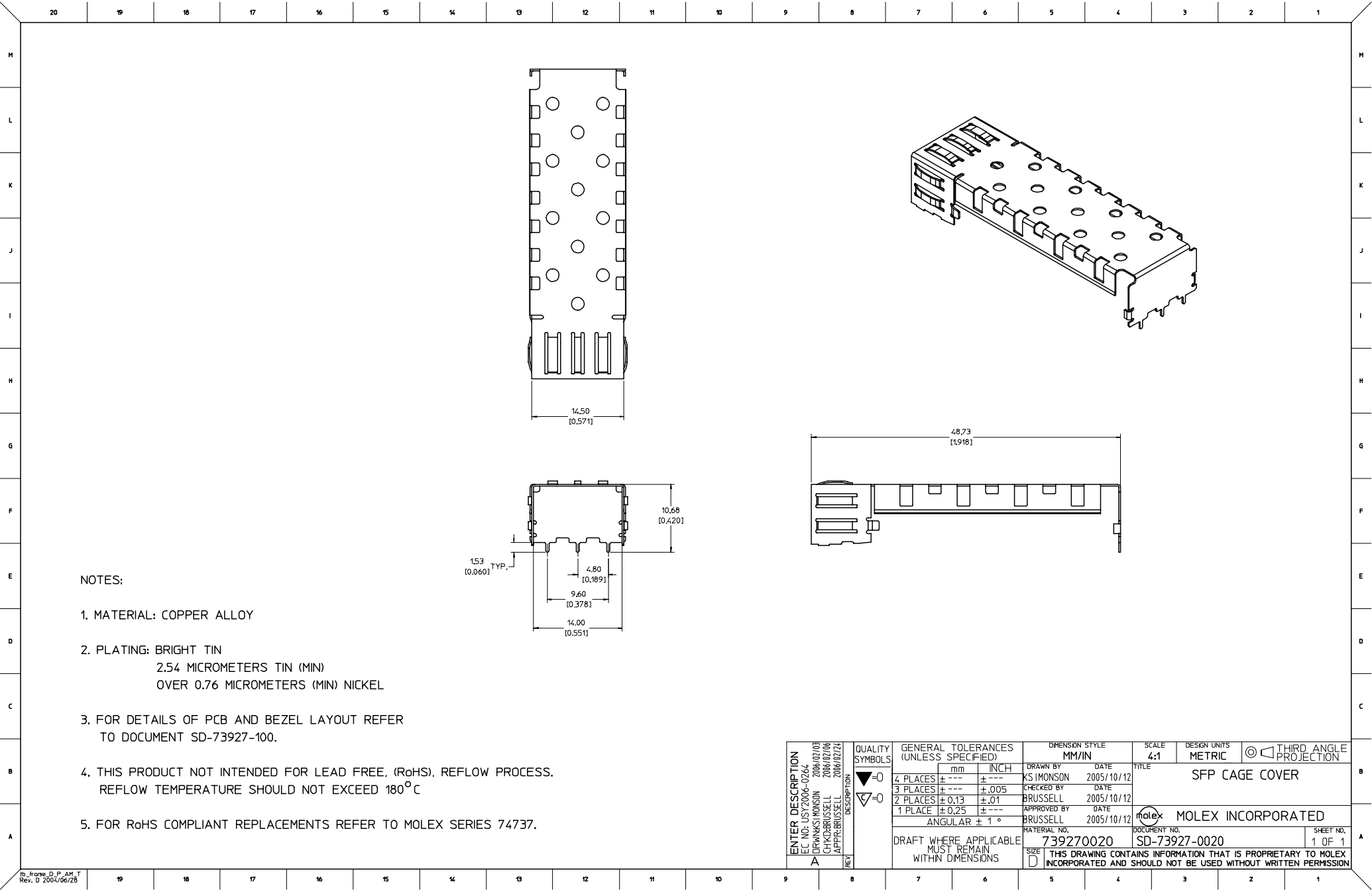
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1 Relational geometry per MSA standard.

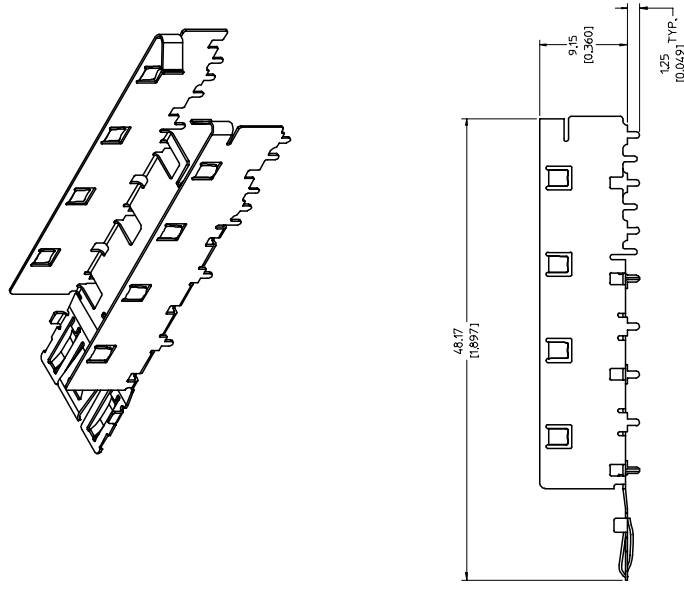
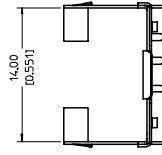
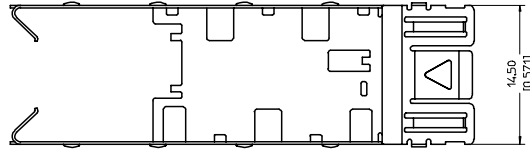
SD UPDATE EC NO: UDT2001-0273 DRWN: DIRKERS 2001/05/01 CHKD: DIRKERS 2001/05/02 APPR: DOOYE 2001/05/03 B	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		REVISE ON CAD ONLY	
				mm	INCH	DIMENSION STYLE IN/MM		TITLE SFP CAGE ASSEMBLY SOLDER POST VERSION		
		▽ = 0	4 PLACES	± ---	± ---	DRAWN BY DATE DIRKERS 2000/09/05	MOLEX INCORPORATED			
			3 PLACES	± ---	± .005					
			2 PLACES	± ---	± ---	CHECKED BY DATE DOYE 2000/09/05				
			1 PLACE	± 0.13	± ---					
			ANGULAR ± 1/2°			APPROVED BY DATE RUSSELL 2000/09/05				MATERIAL NO. 73927-0002
		DRAFT WHERE APPLICABLE			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
MUST REMAIN WITHIN DIMENSIONS										



NOTES:

1. MATERIAL: COPPER ALLOY
2. PLATING: BRIGHT TIN
2.54 MICROMETERS TIN (MIN)
OVER 0.76 MICROMETERS (MIN) NICKEL
3. FOR DETAILS OF PCB AND BEZEL LAYOUT REFER
TO DOCUMENT SD-73927-100.
4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, (RoHS), REFLOW PROCESS.
REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C
5. FOR RoHS COMPLIANT REPLACEMENTS REFER TO MOLEX SERIES 74737.

ENTER DESCRIPTION EC NO. UST2006-0264 DRAWN BY KSI MONSON 2006/07/03 CHKD BY BRUSSELL 2006/07/06 APPR BY BRUSSELL 2006/07/24 REV A	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	TITLE SFP CAGE COVER		
				DRAWN BY KSI MONSON	DATE 2005/10/12	TITLE					
				CHECKED BY BRUSSELL	DATE 2005/10/12	MOLEX MOLEX INCORPORATED					
				APPROVED BY BRUSSELL	DATE 2005/10/12						
				MATERIAL NO. 739270020						DOCUMENT NO. SD-73927-0020	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE D		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



NOTES:

1. MATERIAL: COPPER ALLOY
2. PLATING: BRIGHT TIN
2.54 MICROMETERS TIN (MIN)
OVER 0.76 MICROMETERS (MIN) NICKEL
3. FOR DETAILS OF PCB AND BEZEL LAYOUT REFER
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REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C
5. FOR RoHS COMPLIANT REPLACEMENTS REFER TO MOLEX SERIES 74737.

[illegible]